

GENERAL DESCRIPTION

The 74LVC126A that provides a quad buffer with 3-state output is designed for 1.65V to 3.6V V_{CC} operation. Both 3.3V and 5V devices can drive inputs, enabling this device to operate as a translator in a mixed 3.3V and 5V system environment.

The 3-state outputs are controlled by the output enable input pin (nOE). When nOE is held low, all outputs are disabled. nOE should be connected to GND by using a pull-down resistor to ensure the high-impedance state in the period of power-up or power-down, and the minimum resistance depends on the current-sourcing capability of the driver.

The 74LVC126A is available in Green SOIC-14, TSSOP-14 and TQFN-3.5×3.5-14AL packages. It operates over an ambient temperature range of -40°C to +125°C.

FUNCTION TABLE

INPUTS		OUTPUT
nOE	nA	nY
H	H	H
H	L	L
L	X	Z

H = High Voltage Level

L = Low Voltage Level

X = Don't Care

Z = High-Impedance State

FEATURES

- Wide Supply Voltage Range: 1.65V to 3.6V
- Inputs Accept Voltages up to 5.5V
- Propagation Delay: 3.3ns (TYP) at $V_{CC} = 3.3V$
- Output Ground Bounce V_{OLP} (TYP) < 0.8V at $V_{CC} = 3.3V$ and $T_A = +25^\circ C$
- Output V_{OH} Undershoot V_{OHV} (TYP) > 2V at $V_{CC} = 3.3V$ and $T_A = +25^\circ C$
- 3-State Output
- Separate OE for All 4 Buffers
- Latch-up Performance Exceeds 250mA
- -40°C to +125°C Operating Temperature Range
- Available in Green SOIC-14, TSSOP-14 and TQFN-3.5×3.5-14AL Packages

APPLICATIONS

Battery Powered Equipment

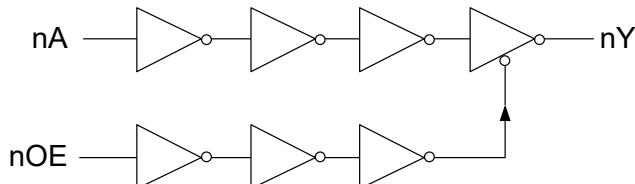
Telecom Equipment

Industrial Equipment

Computing: Server, PC and Notebook

Smartphone

LOGIC DIAGRAM

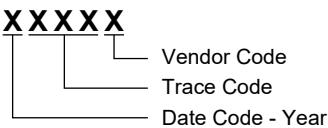


PACKAGE/ORDERING INFORMATION

MODEL	PACKAGE DESCRIPTION	SPECIFIED TEMPERATURE RANGE	ORDERING NUMBER	PACKAGE MARKING	PACKING OPTION
74LVC126A	SOIC-14	-40°C to +125°C	74LVC126AXS14G/TR	08CXS14 XXXXX	Tape and Reel, 2500
	TSSOP-14	-40°C to +125°C	74LVC126AXTS14G/TR	74LVC126A XTS14 XXXXX	Tape and Reel, 4000
	TQFN-3.5×3.5-14AL	-40°C to +125°C	74LVC126AXTSZ14G/TR	SGM083 XTSZ14 XXXXX	Tape and Reel, 4000

MARKING INFORMATION

NOTE: XXXXX = Date Code, Trace Code and Vendor Code.



Green (RoHS & HSF): SG Micro Corp defines "Green" to mean Pb-Free (RoHS compatible) and free of halogen substances. If you have additional comments or questions, please contact your SGMICRO representative directly.

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

Supply Voltage, V _{CC}	-0.5V to 6.5V
Input Voltage, V _I ⁽²⁾	-0.5V to 6.5V
Output Voltage, V _O ⁽²⁾	-0.5V to MIN(6.5V, V _{CC} + 0.5V)
Input Clamp Current, I _{IK} (V _I < 0V)	-50mA
Output Clamp Current, I _{OK} (V _O < 0V)	-50mA
Continuous Output Current, I _O	±50mA
Continuous Current through V _{CC} or GND.....	±100mA
Junction Temperature ⁽³⁾	+150°C
Storage Temperature Range	-65°C to +150°C
Lead Temperature (Soldering, 10s).....	+260°C
ESD Susceptibility	
HBM.....	8000V
CDM	1000V

Input Transition Rise or Fall Rate, Δt/ΔV..... 10ns/V (MAX)
Operating Temperature Range..... -40°C to +125°C

OVERSTRESS CAUTION

- Stresses beyond those listed in Absolute Maximum Ratings may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect reliability. Functional operation of the device at any conditions beyond those indicated in the Recommended Operating Conditions section is not implied.
- The input and output negative voltage ratings may be exceeded if the input and output clamp current ratings are observed.
- The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability.

ESD SENSITIVITY CAUTION

This integrated circuit can be damaged if ESD protections are not considered carefully. SGMICRO recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage. ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because even small parametric changes could cause the device not to meet the published specifications.

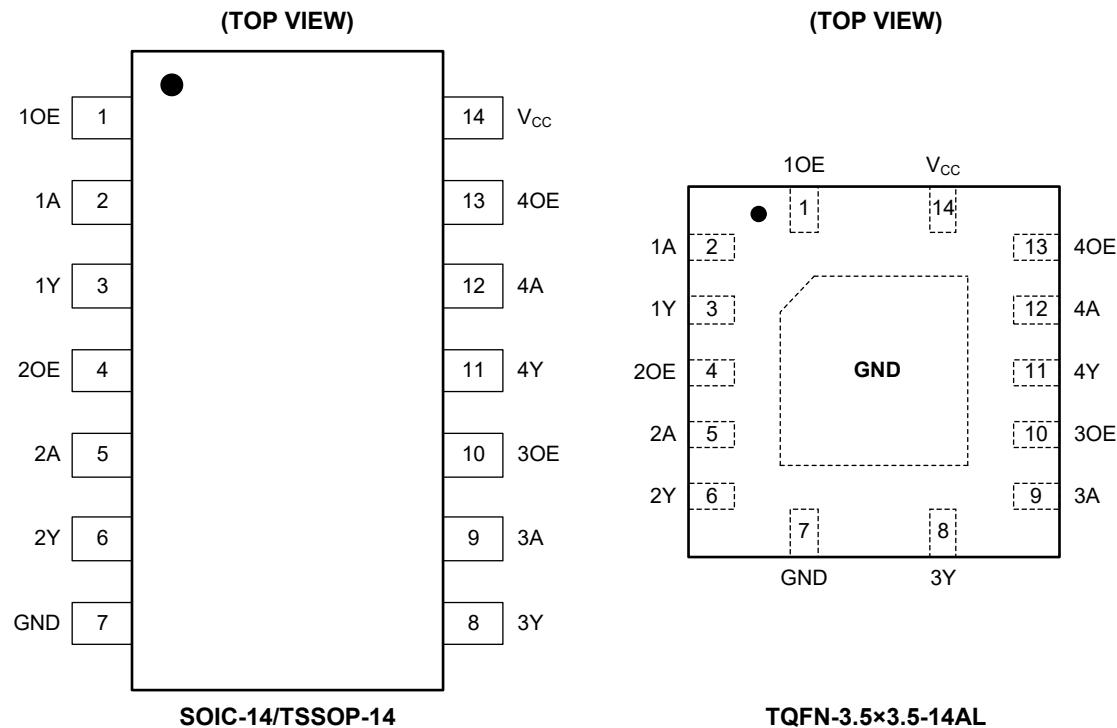
DISCLAIMER

SG Micro Corp reserves the right to make any change in circuit design, or specifications without prior notice.

RECOMMENDED OPERATING CONDITIONS

Supply Voltage, V _{CC}	
Operating	1.65V to 3.6V
Data Retention Only.....	1.5V (MIN)
Input Voltage, V _I	0V to 5.5V
Output Voltage, V _O	0V to V _{CC}
High-Level Output Current, I _{OH}	
V _{CC} = 1.65V.....	-4mA (MAX)
V _{CC} = 2.3V.....	-8mA (MAX)
V _{CC} = 2.7V.....	-12mA (MAX)
V _{CC} = 3.0V.....	-24mA (MAX)
Low-Level Output Current, I _{OL}	
V _{CC} = 1.65V.....	4mA (MAX)
V _{CC} = 2.3V.....	8mA (MAX)
V _{CC} = 2.7V.....	12mA (MAX)
V _{CC} = 3.0V.....	24mA (MAX)

PIN CONFIGURATIONS



PIN DESCRIPTION

PIN		NAME	FUNCTION
SOIC-14/TSSOP-14	TQFN-3.5x3.5-14AL		
1, 4, 10, 13	1, 4, 10, 13	1OE, 2OE, 3OE, 4OE	Output Enable Inputs (Active High).
2, 5, 9, 12	2, 5, 9, 12	1A, 2A, 3A, 4A	Data Inputs.
3, 6, 8, 11	3, 6, 8, 11	1Y, 2Y, 3Y, 4Y	Data Outputs.
7	7	GND	Ground.
14	14	V _{CC}	Supply Voltage.
–	Exposed Pad	GND	Connect it to GND internally. This pad is not an electrical connection point.

ELECTRICAL CHARACTERISTICS(Full = -40°C to +125°C, all typical values are measured at $T_A = +25^\circ\text{C}$ and $V_{CC} = 3.3\text{V}$, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS	TEMP	MIN	TYP	MAX	UNITS
High-Level Input Voltage	V_{IH}	$V_{CC} = 1.65\text{V to } 1.95\text{V}$	Full	$0.65 \times V_{CC}$			V
		$V_{CC} = 2.3\text{V to } 2.7\text{V}$	Full	1.7			
		$V_{CC} = 2.7\text{V to } 3.6\text{V}$	Full	2			
Low-Level Input Voltage	V_{IL}	$V_{CC} = 1.65\text{V to } 1.95\text{V}$	Full			$0.35 \times V_{CC}$	V
		$V_{CC} = 2.3\text{V to } 2.7\text{V}$	Full			0.7	
		$V_{CC} = 2.7\text{V to } 3.6\text{V}$	Full			0.8	
High-Level Output Voltage	V_{OH}	$V_{CC} = 1.65\text{V to } 3.6\text{V}, I_{OH} = -100\mu\text{A}$	Full	$V_{CC} - 0.3$	$V_{CC} - 0.01$		V
		$V_{CC} = 1.65\text{V}, I_{OH} = -4\text{mA}$	Full	1.05	1.52		
		$V_{CC} = 2.3\text{V}, I_{OH} = -8\text{mA}$	Full	1.65	2.16		
		$V_{CC} = 2.7\text{V}, I_{OH} = -12\text{mA}$	Full	2.05	2.53		
		$V_{CC} = 3.0\text{V}, I_{OH} = -12\text{mA}$	Full	2.25	2.85		
		$V_{CC} = 3.0\text{V}, I_{OH} = -24\text{mA}$	Full	2.00	2.68		
Low-Level Output Voltage	V_{OL}	$V_{CC} = 1.65\text{V to } 3.6\text{V}, I_{OL} = 100\mu\text{A}$	Full		0.01	0.3	V
		$V_{CC} = 1.65\text{V}, I_{OL} = 4\text{mA}$	Full		0.07	0.65	
		$V_{CC} = 2.3\text{V}, I_{OL} = 8\text{mA}$	Full		0.11	0.8	
		$V_{CC} = 2.7\text{V}, I_{OL} = 12\text{mA}$	Full		0.15	0.6	
		$V_{CC} = 3.0\text{V}, I_{OL} = 24\text{mA}$	Full		0.29	0.8	
Input Leakage Current	I_I	$V_{CC} = 3.6\text{V}, V_I = 5.5\text{V or GND}$	Full		± 0.1	± 5	μA
OFF-State Output Current	I_{OZ}	$V_{CC} = 3.6\text{V}, V_O = V_{CC} \text{ or GND}$	Full		± 0.1	± 5	μA
Power-Off Leakage Current	I_{OFF}	$V_{CC} = 0\text{V}, V_I \text{ or } V_O = 0\text{V to } 5.5\text{V}$	Full		± 0.1	± 5	μA
Supply Current	I_{CC}	$V_{CC} = 3.6\text{V}, V_I = V_{CC} \text{ or GND}, I_O = 0\text{A}$	Full		0.1	10	μA
Additional Supply Current	ΔI_{CC}	$V_{CC} = 2.7\text{V to } 3.6\text{V, one input at } V_{CC} - 0.6\text{V, other inputs at } V_{CC} \text{ or GND}$	Full		0.1	50	μA
Input Capacitance	C_I	$V_{CC} = 3.3\text{V}, V_I = V_{CC} \text{ or GND}$	+25°C		4.3		pF

DYNAMIC CHARACTERISTICS

(See Figure 1 for test circuit. Full = -40°C to +125°C, all typical values are measured at $T_A = +25^\circ\text{C}$ and $V_{CC} = 1.8\text{V}, 2.5\text{V}, 3.3\text{V}$ and 5V respectively, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS		TEMP	MIN ⁽¹⁾	TYP	MAX ⁽¹⁾	UNITS
Propagation Delay ⁽²⁾	t_{PD}	nA to nY	$V_{CC} = 1.65\text{V to } 1.95\text{V}$	Full	0.5	4.6	12.6	ns
			$V_{CC} = 2.3\text{V to } 2.7\text{V}$	Full	0.5	3.1	6.6	
			$V_{CC} = 2.7\text{V}$	Full	1.5	3.3	6.5	
			$V_{CC} = 3.0\text{V to } 3.6\text{V}$	Full	1	3.3	6	
Enable Time ⁽²⁾	t_{EN}	$n\overline{OE}$ to nY	$V_{CC} = 1.65\text{V to } 1.95\text{V}$	Full	1	7.0	14.2	ns
			$V_{CC} = 2.3\text{V to } 2.7\text{V}$	Full	0.5	3.9	7.9	
			$V_{CC} = 2.7\text{V}$	Full	1.5	4.1	8	
			$V_{CC} = 3.0\text{V to } 3.6\text{V}$	Full	1	3.8	7	
Disable Time ⁽²⁾	t_{DIS}	$n\overline{OE}$ to nY	$V_{CC} = 1.65\text{V to } 1.95\text{V}$	Full	1	7.3	15	ns
			$V_{CC} = 2.3\text{V to } 2.7\text{V}$	Full	0.5	3.8	10	
			$V_{CC} = 2.7\text{V}$	Full	1.5	4.1	10	
			$V_{CC} = 3.0\text{V to } 3.6\text{V}$	Full	1	3.8	10	
Output Skew Time	$t_{SK(O)}$	$V_{CC} = 3.0\text{V to } 3.6\text{V}$		Full			2	ns
Power Dissipation Capacitance ⁽³⁾	C_{PD}	$f = 10\text{MHz}$	$V_{CC} = 1.8\text{V}$	+25°C		11		pF
			$V_{CC} = 2.5\text{V}$	+25°C		12		
			$V_{CC} = 3.3\text{V}$	+25°C		13		

NOTES:

1. Specified by design and characterization; not production tested.
2. t_{PD} is the same as t_{PLH} and t_{PHL} . t_{EN} is the same as t_{PZH} and t_{PZL} . t_{DIS} is the same as t_{PLZ} and t_{PHZ} .
3. C_{PD} is used to determine the dynamic power dissipation (P_D in μW).

$$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \sum(C_L \times V_{CC}^2 \times f_o)$$

where:

f_i = Input frequency in MHz.

f_o = Output frequency in MHz.

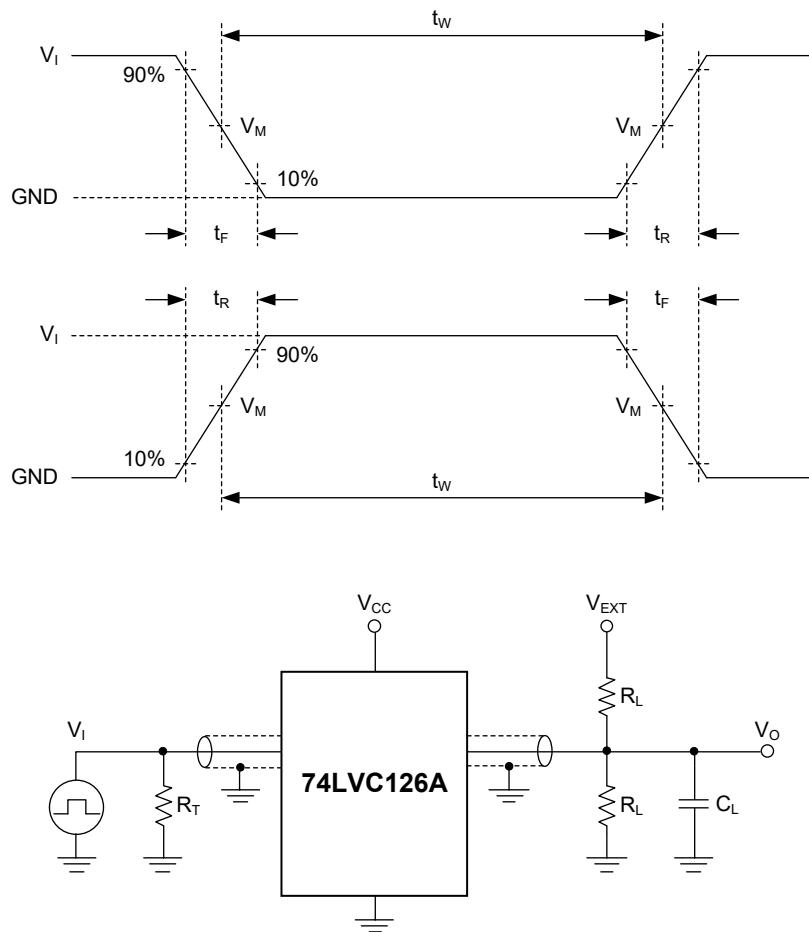
C_L = Output load capacitance in pF.

V_{CC} = Supply voltage in Volts.

N = Number of inputs switching.

$\sum(C_L \times V_{CC}^2 \times f_o)$ = Sum of outputs.

TEST CIRCUIT



Test conditions are given in Table 1.

Definitions for test circuit:

R_L : Load resistance.

C_L : Load capacitance (includes jig and probe).

R_T : Termination resistance (equals to output impedance Z_O of the pulse generator).

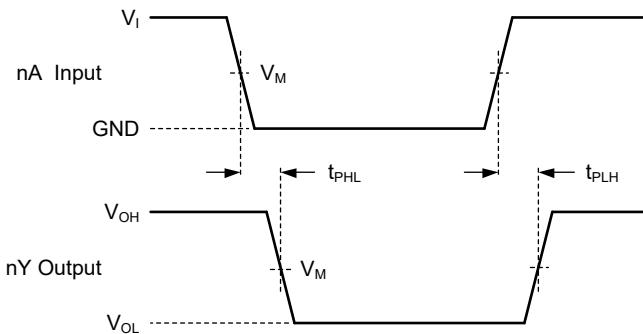
V_{EXT} : External voltage is used to measure switching time.

Figure 1. Test Circuit for Measuring Switching Times

Table 1. Test Conditions

SUPPLY VOLTAGE	INPUT		LOAD		V _{EXT}		
	V _{CC}	V _I	t _R , t _F	C _L	R _L	t _{PLH} , t _{PHL}	t _{PZL} , t _{PZL}
1.8V ± 0.15V	V _{CC}	≤ 2.0ns	30pF	1kΩ	Open	2 × V _{CC}	GND
2.5V ± 0.2V	V _{CC}	≤ 2.0ns	30pF	500Ω	Open	2 × V _{CC}	GND
2.7V	2.7V	≤ 2.5ns	50pF	500Ω	Open	2 × V _{CC}	GND
3.3V ± 0.3V	2.7V	≤ 2.5ns	50pF	500Ω	Open	2 × V _{CC}	GND

WAVEFORMS

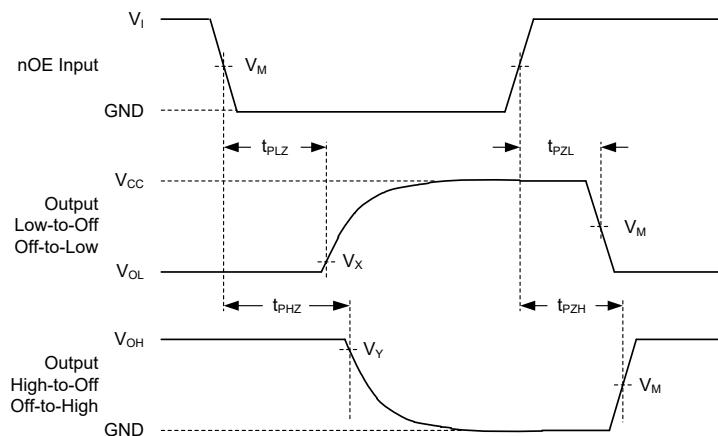


Test conditions are given in Table 1.

Measurement points are given in Table 2.

Logic levels: V_{OL} and V_{OH} are typical output voltage levels that occur with the output load.

Figure 2. Input nA to Output nY Propagation Delays



Test conditions are given in Table 1.

Measurement points are given in Table 2.

Logic levels: V_{OL} and V_{OH} are typical output voltage levels that occur with the output load.

Figure 3. 3-State Enable and Disable Times

Table 2. Measurement Points

SUPPLY VOLTAGE	INPUT		OUTPUT		
	V_I	$V_M^{(1)}$	V_M	V_X	V_Y
$1.8V \pm 0.15V$	V_{CC}	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$	$V_{OL} + 0.15V$	$V_{OH} - 0.15V$
$2.5V \pm 0.2V$	V_{CC}	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$	$V_{OL} + 0.15V$	$V_{OH} - 0.15V$
$2.7V$	$2.7V$	$1.5V$	$1.5V$	$V_{OL} + 0.3V$	$V_{OH} - 0.3V$
$3.3V \pm 0.3V$	$2.7V$	$1.5V$	$1.5V$	$V_{OL} + 0.3V$	$V_{OH} - 0.3V$

NOTE:

1. The measurement points should be V_{IH} or V_{IL} when the input rising or falling time exceeds 2.5ns.

REVISION HISTORY

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

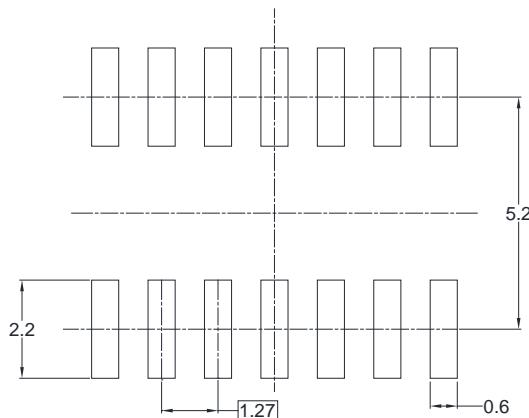
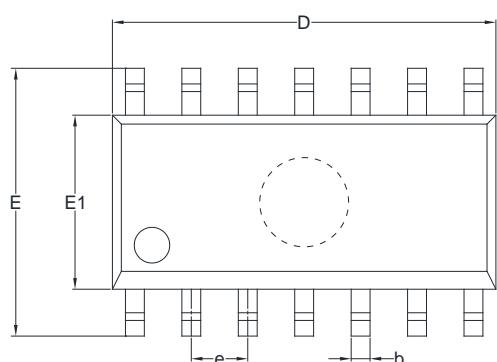
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Updated the package outline dimensions of TQFN-3.5×3.5-14AL.....	11

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Changed from product preview to production data.....	All

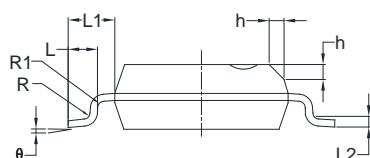
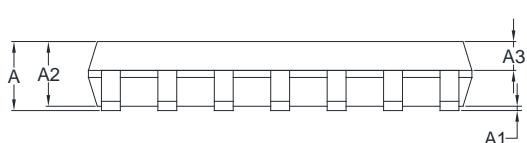
PACKAGE INFORMATION

PACKAGE OUTLINE DIMENSIONS

SOIC-14



RECOMMENDED LAND PATTERN (Unit: mm)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MIN	MAX	MIN	MAX
A	1.35	1.75	0.053	0.069
A1	0.10	0.25	0.004	0.010
A2	1.25	1.65	0.049	0.065
A3	0.55	0.75	0.022	0.030
b	0.36	0.49	0.014	0.019
D	8.53	8.73	0.336	0.344
E	5.80	6.20	0.228	0.244
E1	3.80	4.00	0.150	0.157
e	1.27 BSC		0.050 BSC	
L	0.45	0.80	0.018	0.032
L1	1.04 REF		0.040 REF	
L2	0.25 BSC		0.01 BSC	
R	0.07		0.003	
R1	0.07		0.003	
h	0.30	0.50	0.012	0.020
θ	0°	8°	0°	8°

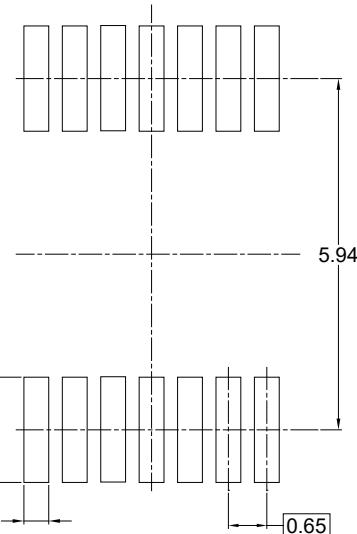
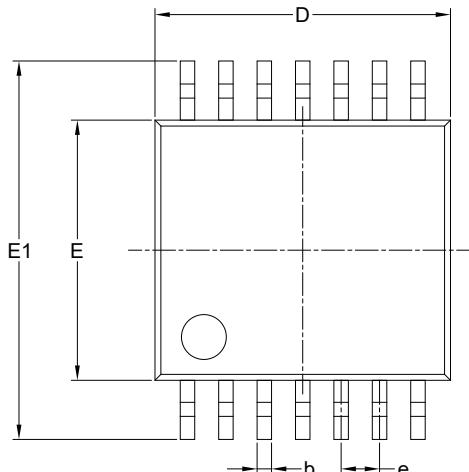
NOTES:

1. Body dimensions do not include mode flash or protrusion.
2. This drawing is subject to change without notice.

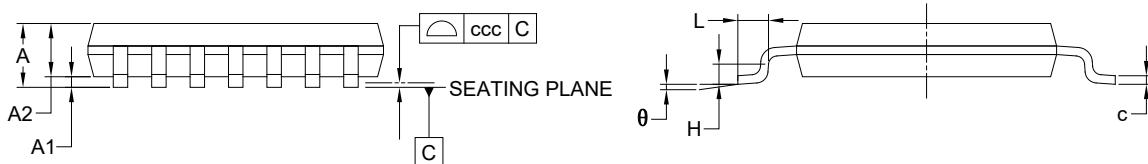
PACKAGE INFORMATION

PACKAGE OUTLINE DIMENSIONS

TSSOP-14



RECOMMENDED LAND PATTERN (Unit: mm)



Symbol	Dimensions In Millimeters		
	MIN	MOD	MAX
A	-	-	1.200
A1	0.050	-	0.150
A2	0.800	-	1.050
b	0.190	-	0.300
c	0.090	-	0.200
D	4.860	-	5.100
E	4.300	-	4.500
E1	6.200	-	6.600
e	0.650 BSC		
L	0.450	-	0.750
H	0.250 TYP		
θ	0°	-	8°
ccc	0.100		

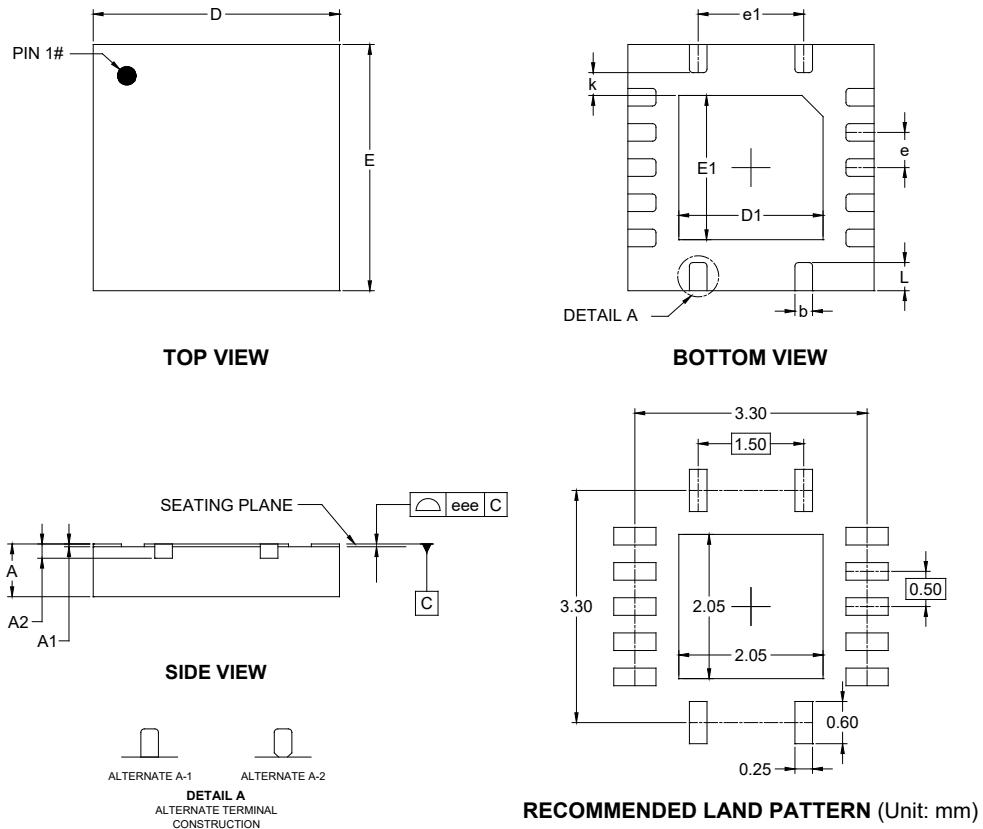
NOTES:

1. This drawing is subject to change without notice.
2. The dimensions do not include mold flashes, protrusions or gate burrs.
3. Reference JEDEC MO-153.

PACKAGE INFORMATION

PACKAGE OUTLINE DIMENSIONS

TQFN-3.5x3.5-14AL



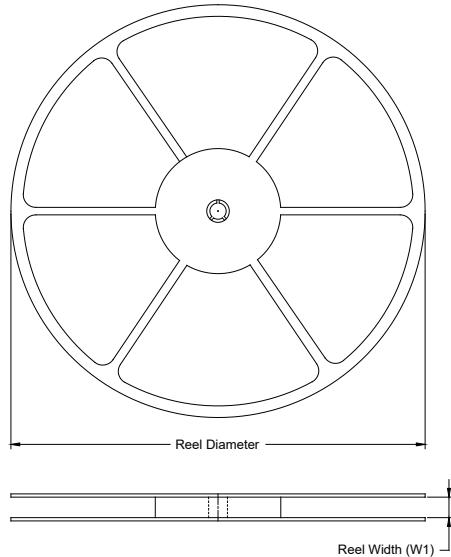
Symbol	Dimensions In Millimeters		
	MIN	MOD	MAX
A	0.700	-	0.800
A1	0.000	-	0.050
A2	0.203 REF		
b	0.200	-	0.300
D	3.400	-	3.600
E	3.400	-	3.600
D1	1.950	-	2.150
E1	1.950	-	2.150
e	0.500 BSC		
e1	1.500 BSC		
k	0.200 MIN		
L	0.300	-	0.500
eee	0.080		

NOTE: This drawing is subject to change without notice.

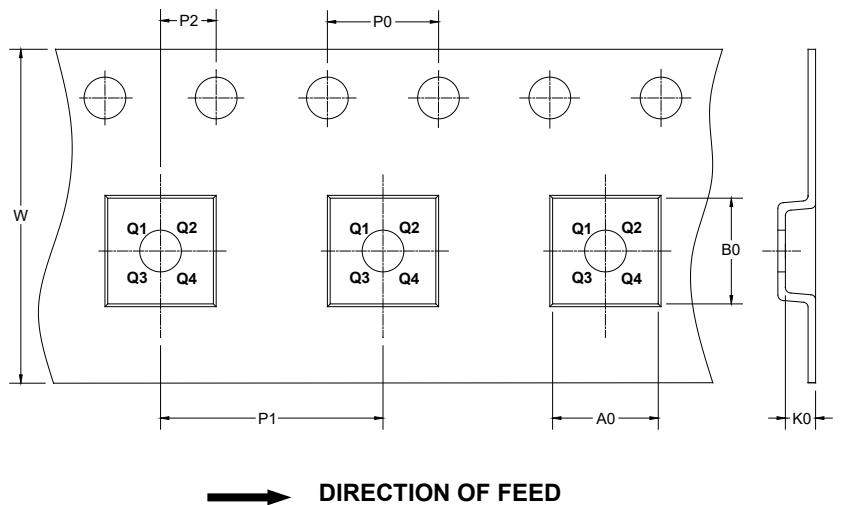
PACKAGE INFORMATION

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



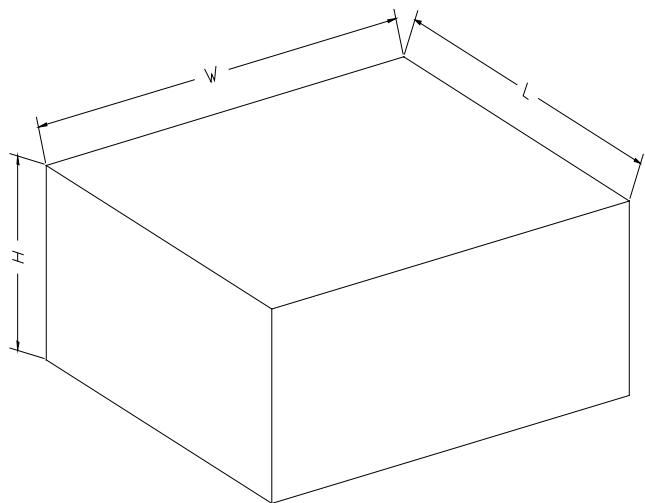
NOTE: The picture is only for reference. Please make the object as the standard.

KEY PARAMETER LIST OF TAPE AND REEL

Package Type	Reel Diameter	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pin1 Quadrant
SOIC-14	13"	16.4	6.60	9.30	2.10	4.0	8.0	2.0	16.0	Q1
TSSOP-14	13"	12.4	6.80	5.40	1.50	4.0	8.0	2.0	12.0	Q1
TQFN-3.5×3.5-14AL	13"	12.4	3.80	3.80	1.10	4.0	8.0	2.0	12.0	Q1

PACKAGE INFORMATION

CARTON BOX DIMENSIONS



NOTE: The picture is only for reference. Please make the object as the standard.

KEY PARAMETER LIST OF CARTON BOX

Reel Type	Length (mm)	Width (mm)	Height (mm)	Pizza/Carton
13"	386	280	370	5

00002